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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	RL78
Core Size	16-Bit
Speed	24MHz
Connectivity	CSI, I²C, LINbus, UART/USART
Peripherals	DMA, LCD, LVD, POR, PWM, WDT
Number of I/O	58
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-LQFP
Supplier Device Package	80-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f10wmcafa-30

(3/3)

<R>

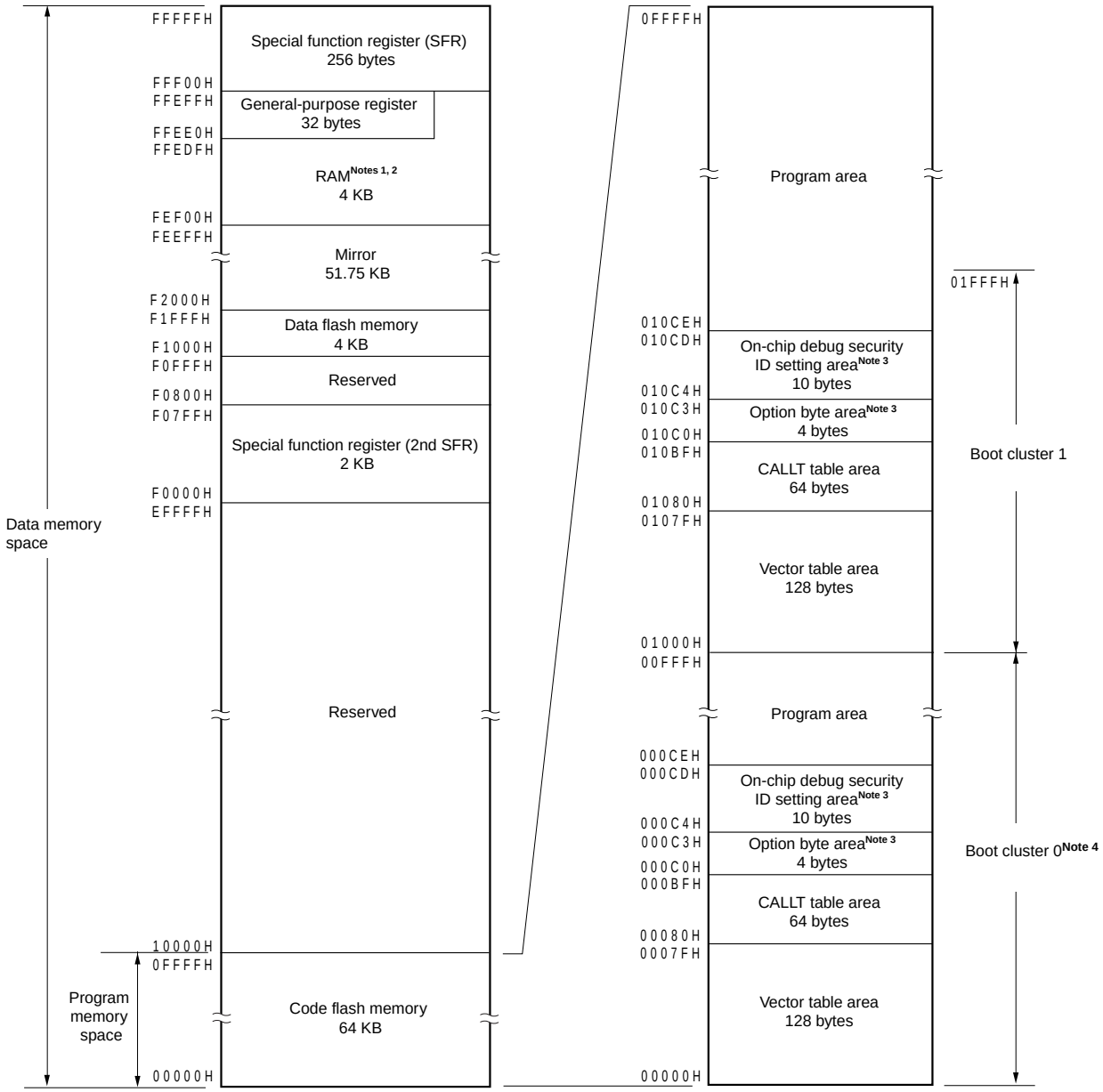
Function Name	Pin Type	I/O	After Reset Release	Alternate Function	Function
P60	12-1-3	I/O	Input port	SCLA0/(TI01)/(TO01)	Port 6. 2-bit I/O port. Input/output can be specified in 1-bit units. N-ch open-drain output (6 V tolerance).
P61				SDAA0/(TI02)/(TO02)	
P70	7-5-4	I/O	Digital input invalid Note 1	KR0/SEG12	Port 7. 8-bit I/O port. Input/output can be specified in 1-bit units. Use of an on-chip pull-up resistor can be specified by a software setting at input port. Can be set to LCD output Note 2.
P71				KR1/SEG13	
P72				KR2/SEG14	
P73				KR3/SEG15	
P74	7-5-16			KR4/SEG16/TKBO00	
P75				KR5/SEG17/TKBO01-2	
P76				KR6/SEG18/TKBO01-1	
P77				KR7/SEG19/TKBO01-0	
P121	2-2-1	Input	Input port	X1	Port 12. 3-bit I/O port and 4-bit input only port. For P125 to P127, input/output can be specified in 1-bit units. For P125 to P127, use of an on-chip pull-up resistor can be specified by a software setting at input port. P125 to P127 can be set to LCD output Note 2.
P122				X2/EXCLK	
P123				XT1	
P124				XT2/EXCLKS	
P125	7-5-6	I/O	Digital input invalid Note 1	V_{L3}/(TI06)/(TO06)	
P126	7-5-5			CAPL/(TI04)/(TO04)	
P127				CAPH/(TI03)/(TO03)/(REMOOUT)	
P130	7-5-10	I/O	Digital input invalid Note 1	(SO00)/(TxD0)/SEG28	Port 13. 1-bit I/O port and 1-bit input only port. For P130, input/output can be specified. For P130, use of an on-chip pull-up resistor can be specified by a software setting at input port. Output of P130 can be set to N-ch open-drain output (V_{DD} tolerance). P130 can be set to LCD output Note 2.
P137	2-1-2	Input	Input port	INTP0	
$\overline{\text{RESET}}$	2-1-1	Input	–	–	Input only pin for external reset. When external reset is not used, connect this pin to V_{DD} directly or via a resistor.

Notes 1. “Digital input invalid” refers to the state in which all the digital outputs, digital inputs, analog inputs, and LCD outputs are disabled.

2. Digital or LCD for each pin can be selected with the port mode register x (PMx) and the LCD port function register x (PFSEGx) (can be set in 1-bit unit).

Remark Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). See **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)**.

Figure 3-4. Memory Map (R5F10WLE, R5F10WME)



Notes 1. Do not allocate RAM addresses which are used as a stack area, a data buffer, a branch destination of vector interrupt processing, and a DMA transfer destination/transfer source to the area FFE20H to FFEDFH when performing self-programming and rewriting the data flash memory.

2. Instructions can be executed from the RAM area excluding the general-purpose register area.

3. When boot swap is not used: Set the option bytes to 000C0H to 000C3H, and the on-chip debug security IDs to 000C4H to 000CDH.

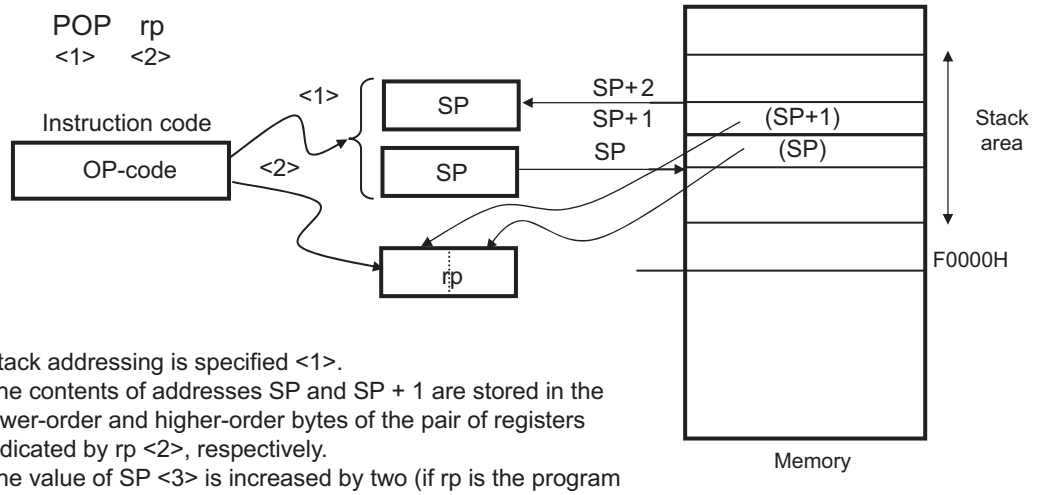
When boot swap is used: Set the option bytes to 000C0H to 000C3H and 010C0H to 010C3H, and the on-chip debug security IDs to 000C4H to 000CDH and 010C4H to 010CDH.

4. Writing boot cluster 0 can be prohibited depending on the setting of security (see **28.6 Security Setting**).

Caution While RAM parity error resets are enabled (RPERDIS = 0), be sure to initialize RAM areas where data access is to proceed and the RAM area + 10 bytes when instructions are fetched from RAM areas, respectively.

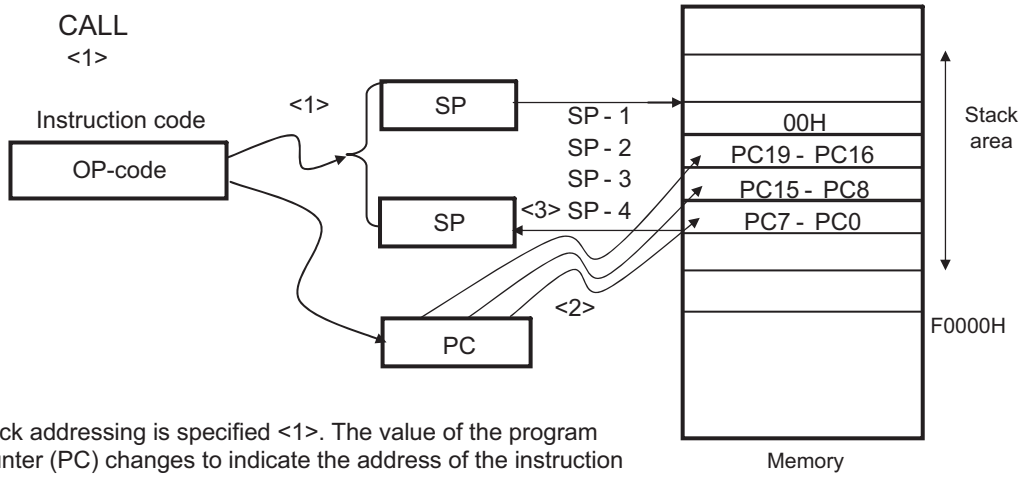
Reset signal generation sets RAM parity error resets to enabled (RPERDIS = 0). For details, see 25.3.3 RAM parity error detection function.

Figure 3-38. Example of POP



- Stack addressing is specified <1>.
- The contents of addresses SP and SP + 1 are stored in the lower-order and higher-order bytes of the pair of registers indicated by rp <2>, respectively.
- The value of SP <3> is increased by two (if rp is the program status word (PSW), the content of address SP + 1 is stored in the PSW).

Figure 3-39. Example of CALL, CALLT



- Stack addressing is specified <1>. The value of the program counter (PC) changes to indicate the address of the instruction following the CALL instruction.
- 00H, the values of PC bits 19 to 16, 15 to 8, and 7 to 0 are stored in addresses SP - 1, SP - 2, SP - 3, and SP - 4, respectively <2>.
- The value of the SP <3> is decreased by 4.

7.4.5 Standalone mode (period controlled by TKBCR00)

(1) Outline of functions

In standalone operation mode, the period is defined according to the value of TKBCR00, TKBO00 is generated by TKBCR00 and TKBCR01, and then TKBO01-0, TKBO01-1, and TKBO01-2 are generated by TKBCR02 and TKBCR03.

The duty can be set within a range of 0% to 100% and the period and duty can be calculated using the following formula.

[Calculation Formula for TKBO00 Output]

Pulse period = (TKBCR00 setting + 1) × Count clock period

Duty [%] = (TKBCR01 setting / (TKBCR00 setting + 1)) × 100

0% output: TKBCR01 setting = 0000H

100% output: TKBCR01 setting ≥ TKBCR00 setting + 1

[Calculation Formula for TKBO01-0, TKBO01-1, TKBO01-2 Output]

Duty [%] = ((TKBCR03 setting – TKBCR02 setting) / (TKBCR00 setting + 1)) × 100

0% output: TKBCR03 setting = TKBCR02 setting

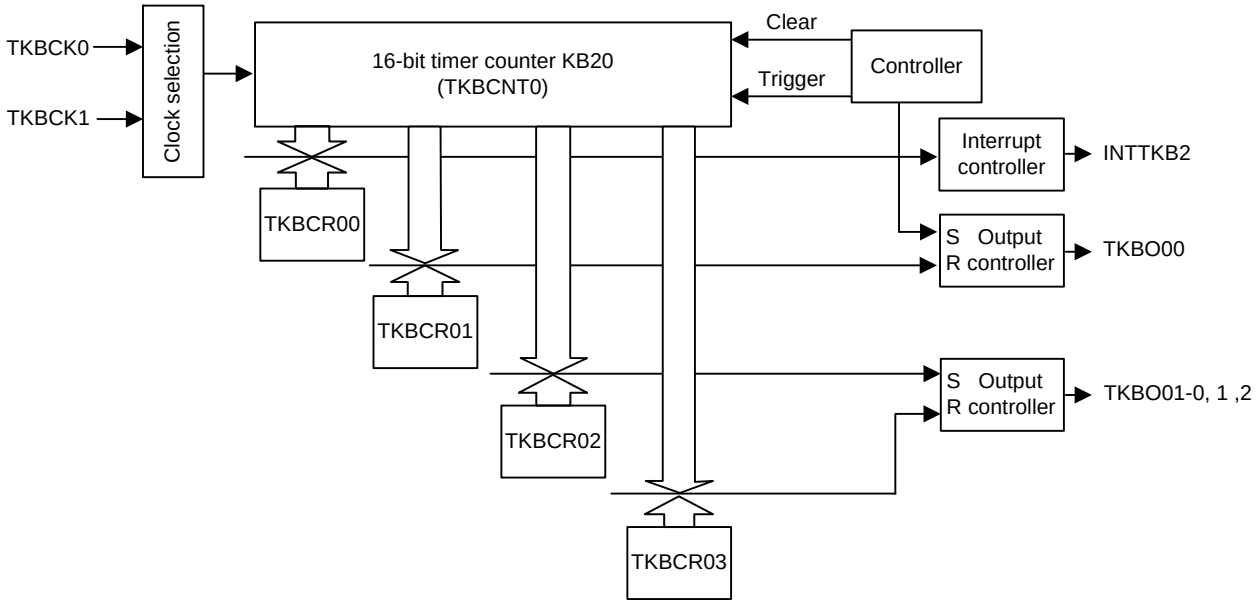
100% output: TKBCR02 setting = 0000H

TKBCR03 setting ≥ TKBCR00 setting + 1

Caution It should always be: TKBCR02 setting ≤ TKBCR03 setting.

Figure 7-40 shows the configuration of standalone mode (period controlled by TKBCR00).

Figure 7-40. Configuration of Standalone Mode (Period Controlled by TKBCR00)

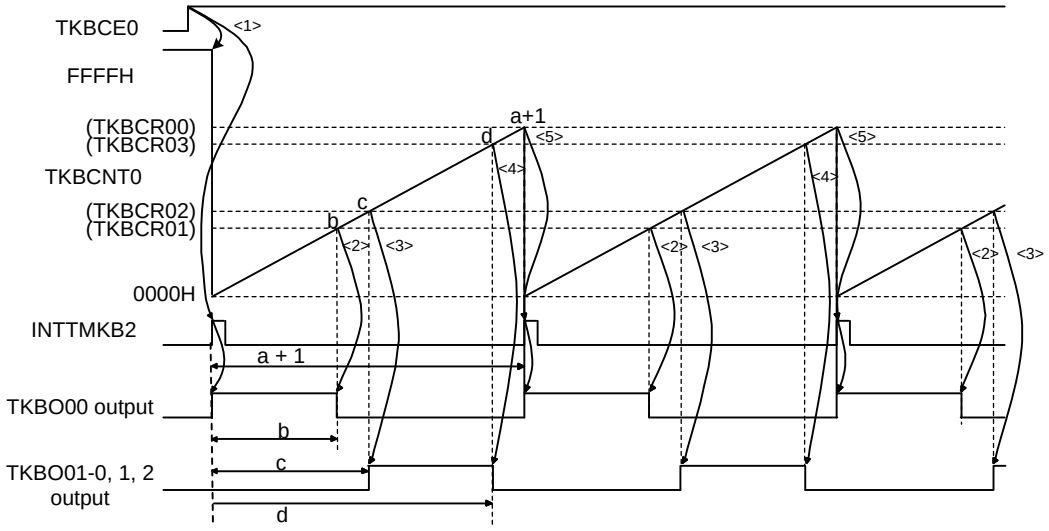


Remark Output from TKBO01-0, TKBO01-1, and TKBO01-2 is switched by the 16-bit timer KB2 switch register (PWCTKB).

(2) Outline of operation

Figure 7-41 shows the timing sample for standalone mode.

Figure 7-41. Timing Sample for Standalone Mode (Period Controlled by TKBCR00)
(When default value of output is low level (TKBTOD0p = 0) and active level is high level (TKBTOL0p = 0))



This section describes an example about the standalone operation (periodic controlled by TKBCR00). The following descriptions are linked with <1> to <5> in Figure 7-41.

<1> When TKBCE0 is set to 1, 16-bit timer counter KB2 (TKBCNT0) changes from FFFFH to 0000H in synchronization with the count clock, then it starts counting up. At the same time, INTTMKB2 output is generated and TKBO00 output changes from its default value specified with the TKB0TOD00 bit in TKB0IOC00 register to its active value (high level in this example) specified with the TKB0TOL00 bit (TKBO01-0, TKBO01-1, TKBO01-2 output holds its default value specified with the TKB0TOD01 bit).

<2> When TKBCNT0 is counted up and its value matches the value specified in 16-bit timer KB2 compare register 01 (TKBCR01), TKBO00 output becomes inactive level.

<3> When TKBCNT0 is counted up and its value matches the value specified in 16-bit timer KB2 compare register 02 (TKBCR02), TKBO01-0, TKBO01-1, TKBO01-2 output becomes active level.

<4> When TKBCNT0 is counted up and its value matches the value specified in 16-bit timer KB2 compare register 03 (TKBCR03), TKBO01-0, TKBO01-1, TKBO01-2 output becomes inactive level.

<5> When TKBCNT0 is counted up and its value matches the value specified in 16-bit timer KB2 compare register 00 (TKBCR00), INTTMKB2 output is generated at the next count clock and TKBO00 output becomes active level. TKBCNT0 starts its upward counting from 0000H.

<6> Repeats <2> through <5>.

9.3 Registers Controlling 12-bit Interval Timer

The 12-bit interval timer is controlled by the following registers.

- Peripheral enable register 1 (PER1)
- Subsystem clock supply mode control register (OSMC)
- 12-bit interval timer control register (ITMC)

9.3.1 Peripheral enable register 1 (PER1)

This register is used to enable or disable supplying the clock to the peripheral hardware. Clock supply to a hardware macro that is not used is stopped in order to reduce the power consumption and noise.

When the 12-bit interval timer is used, be sure to set bit 7 (TMKAEN) of this register to 1.

The PER1 register can be set by a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation clears this register to 00H.

Figure 9-2. Format of Peripheral Enable Register 1 (PER1)

Address: F007AH After reset: 00H R/W

Symbol	<7>	6	<5>	<4>	3	2	1	0
PER1	TMKAEN	0	CMPEN	TKB2EN	0	0	0	0

TMKAEN	Control of 12-bit interval timer input clock supply
0	Stops input clock supply. • SFRs used by the 12-bit interval timer cannot be written. • The 12-bit interval timer is in the reset status.
1	Enables input clock supply. • SFRs used by the 12-bit interval timer can be read and written.

Cautions 1. When using the 12-bit interval timer, first set the TMKAEN bit to 1. If TMKAEN = 0, writing to a control register of the 12-bit interval timer is ignored, and, even if the register is read, only the default value is read (except the subsystem clock supply mode control register (OSMC)).

2. Clock supply to peripheral functions other than real-time clock 2, 12-bit interval timer, clock output/buzzer output, and LCD controller/driver can be stopped in HALT mode when the subsystem clock is used, by setting the RTCLPC bit of the subsystem clock supply mode control register (OSMC) to 1. In this case, set the TMKAEN bit of the PER1 register to 1 and the other bits (bits 0 to 6) to 0.

3. Be sure to clear the bits 0 to 3 and 6 to 0.

12.6.6 Hardware trigger wait mode (one-shot conversion mode)

<1> In the stop status, the ADCE bit of A/D converter mode register 0 (ADM0) is set to 1, and the system enters the hardware trigger standby status.

<2> If a hardware trigger is input while in the hardware trigger standby status, A/D conversion is performed on the analog input specified by the analog input channel specification register (ADS). The ADCS bit of the ADM0 register is automatically set to 1 according to the hardware trigger input.

<3> When A/D conversion ends, the conversion result is stored in the A/D conversion result register (ADCR, ADCRH), and the A/D conversion end interrupt request signal (INTAD) is generated.

<4> After A/D conversion ends, the ADCS bit is automatically cleared to 0, and the A/D converter enters the stop status.

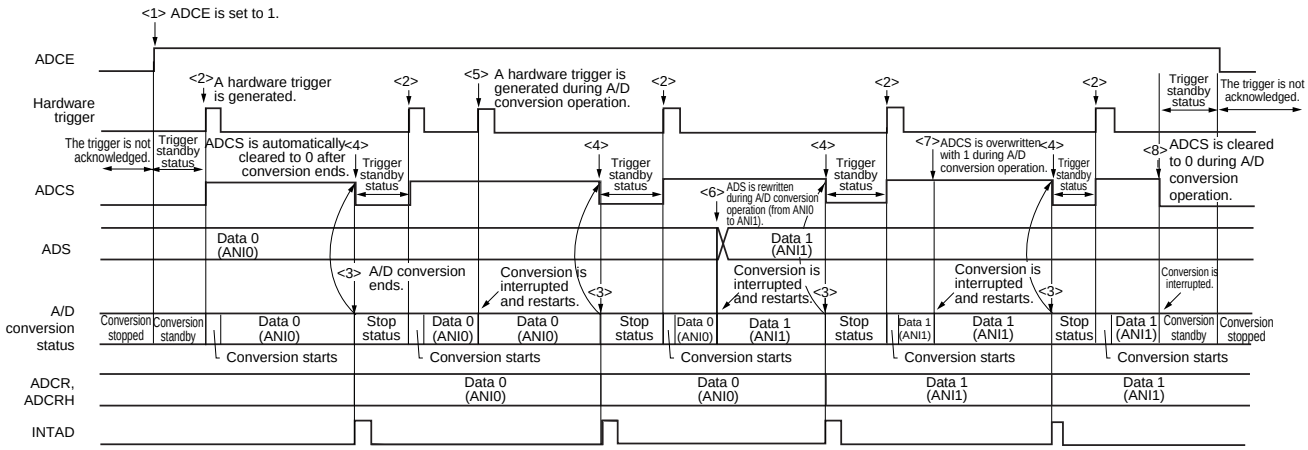
<5> If a hardware trigger is input during conversion operation, the current A/D conversion is interrupted, and conversion restarts. The partially converted data is discarded.

<6> When the value of the ADS register is rewritten or overwritten during conversion operation, the current A/D conversion is interrupted, and A/D conversion is performed on the analog input respecified by the ADS register. The partially converted data is discarded.

<7> When ADCS is overwritten with 1 during conversion operation, the current A/D conversion is interrupted, and conversion restarts. The partially converted data is initialized.

<8> When ADCS is cleared to 0 during conversion operation, the current A/D conversion is interrupted, the system enters the hardware trigger standby status, and the A/D converter enters the stop status. When ADCE = 0, inputting a hardware trigger is ignored and A/D conversion does not start.

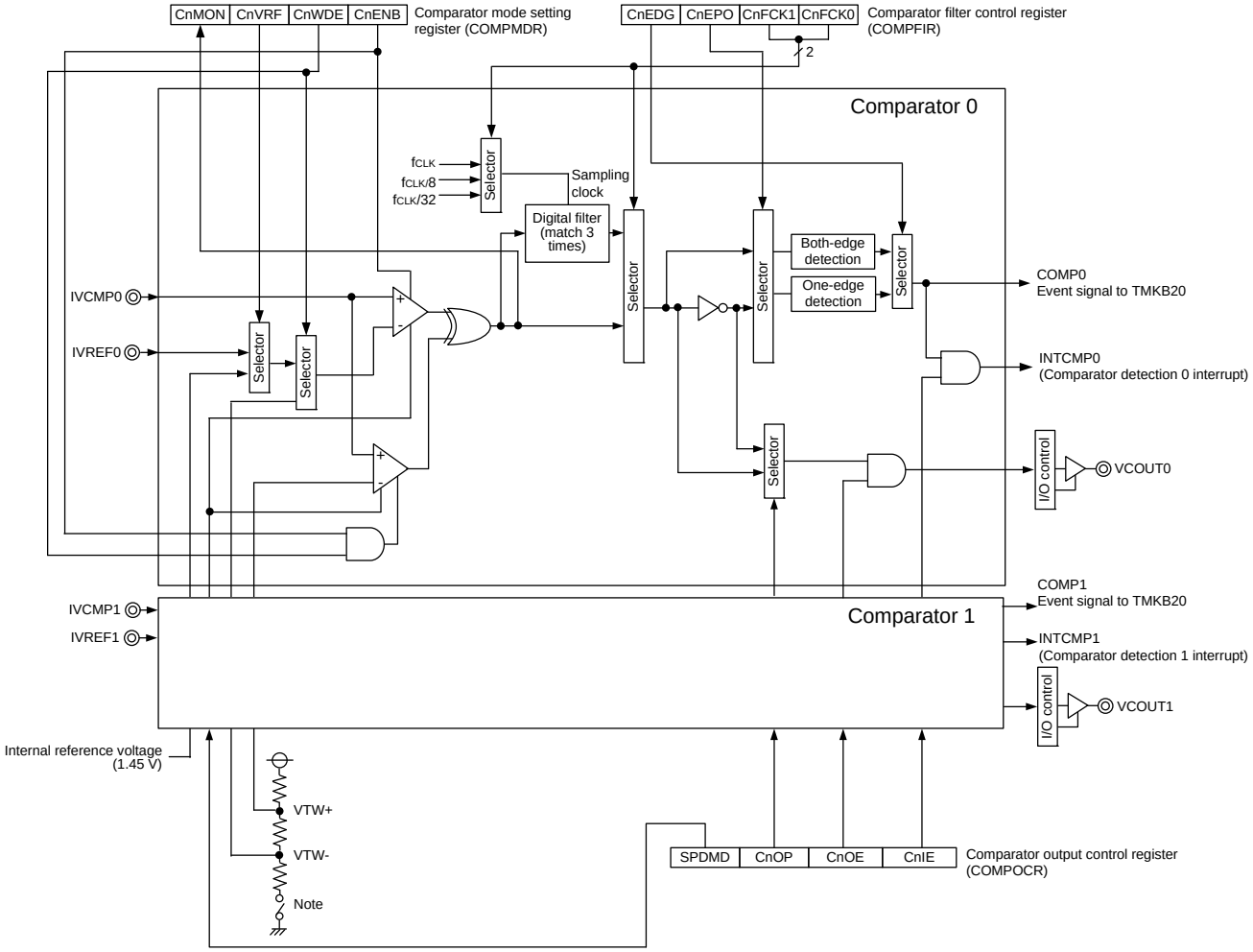
Figure 12-22. Example of Hardware Trigger Wait Mode (One-Shot Conversion Mode) Operation Timing



13.2 Configuration of Comparator

Figure 13-1 shows the comparator block diagram.

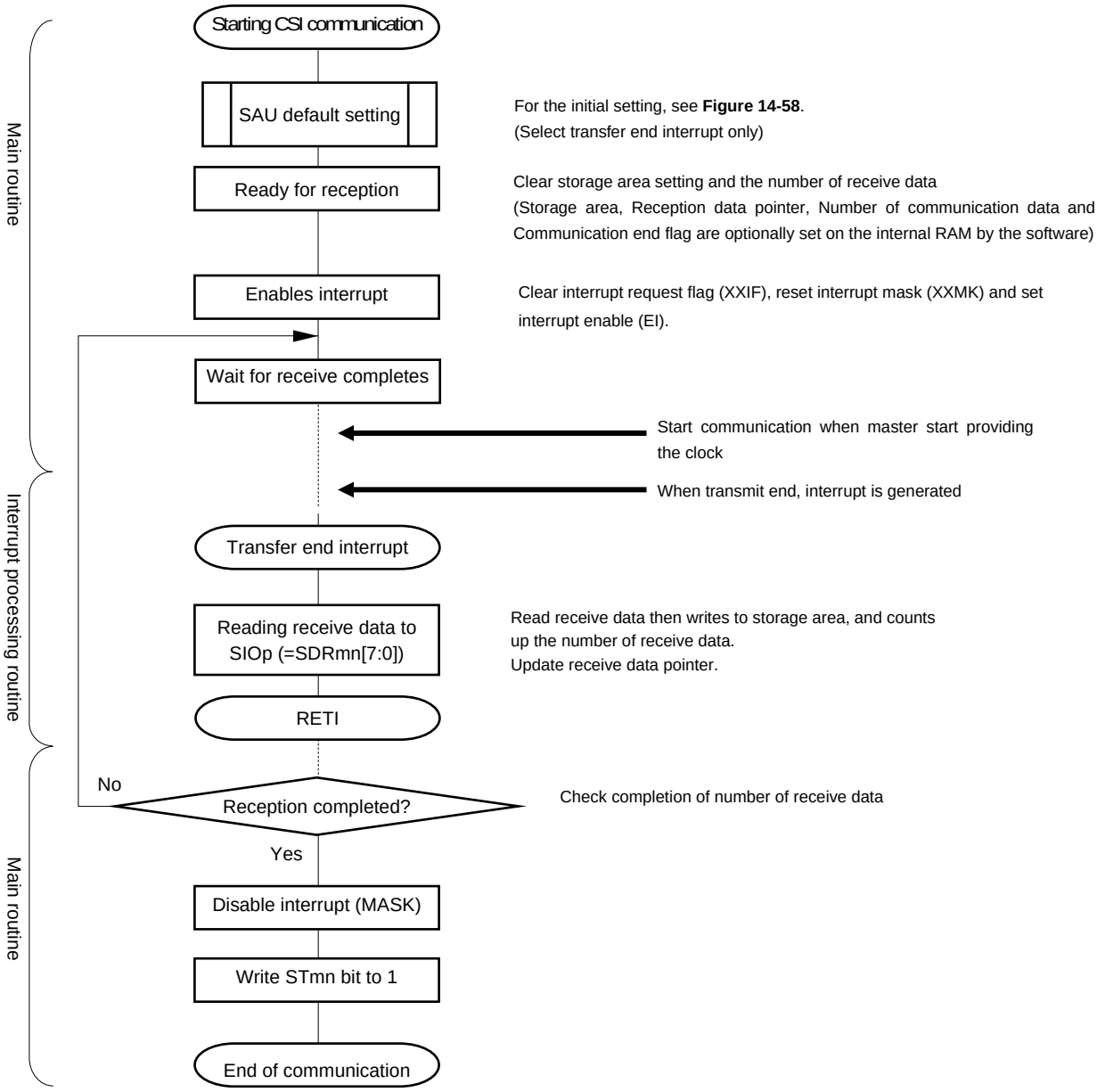
Figure 13-1. Comparator Block Diagram



Note When either or both of the C0WDE and C1WDE bits are set to 1, this switch is turned on and the divider resistors for generating the comparison voltage are enabled.

Remark n = 0, 1

Figure 14-62. Flowchart of Slave Reception (in Single-Reception Mode)



15.5.14 Communication reservation

(1) When communication reservation function is enabled (bit n (IICRSVn) of IICA flag register n (IICFn) = 0)

To start master device communications when not currently using a bus, a communication reservation can be made to enable transmission of a start condition when the bus is released. There are two modes under which the bus is not used.

- When arbitration results in neither master nor slave operation
- When an extension code is received and slave operation is disabled (ACK is not returned and the bus was released by setting bit 6 (LRELn) of IICA control register n0 (IICCTLn0) to 1 and saving communication).

If bit 1 (STTn) of the IICCTLn0 register is set to 1 while the bus is not used (after a stop condition is detected), a start condition is automatically generated and wait state is set.
If an address is written to the IICA shift register n (IICAn) after bit 4 (SPIEn) of the IICCTLn0 register was set to 1, and it was detected by generation of an interrupt request signal (INTIICAn) that the bus was released (detection of the stop condition), then the device automatically starts communication as the master. Data written to the IICAn register before the stop condition is detected is invalid.
When the STTn bit has been set to 1, the operation mode (as start condition or as communication reservation) is determined according to the bus status.

- If the bus has been released ..... a start condition is generated
- If the bus has not been released (standby mode)..... communication reservation

Check whether the communication reservation operates or not by using the MSTSn bit (bit 7 of the IICA status register n (IICSn)) after the STTn bit is set to 1 and the wait time elapses.
Use software to secure the wait time calculated by the following expression.

<R>

Wait time from setting STTn = 1 to checking the MSTSn flag:
(IICWLn setting value + IICWHn setting value + 4) / f_{MCK} + $t_F \times 2$

Remarks 1. IICWLn: IICA low-level width setting register n
IICWHn: IICA high-level width setting register n
t_F: SDAAn and SCLAn signal falling times
f_{MCK}: IICA operation clock frequency

2. n = 0

(3) Output waveforms of common and segment signals

The voltages listed in Table 16-14 are output as common and segment signals.

When both common and segment signals are at the select voltage, a display on-voltage of $\pm V_{LCD}$ is obtained. The other combinations of the signals correspond to the display off-voltage.

Table 16-14. LCD Drive Voltage

(a) Static display mode

Common Signal \ Segment Signal	Select Signal Level	Deselect Signal Level
	V_{SS}/V_{L4}	V_{L4}/V_{SS}
V_{L4}/V_{SS}	$-V_{LCD}/+V_{LCD}$	0 V/0 V

(b) 1/2 bias method

Common Signal	Segment Signal	Select Signal Level	Deselect Signal Level
		V_{SS}/V_{L4}	V_{L4}/V_{SS}
Select signal level	V_{L4}/V_{SS}	$-V_{LCD}/+V_{LCD}$	0 V/0 V
Deselect signal level	V_{L2}	$-\frac{1}{2}V_{LCD}/+\frac{1}{2}V_{LCD}$	$+\frac{1}{2}V_{LCD}/-\frac{1}{2}V_{LCD}$

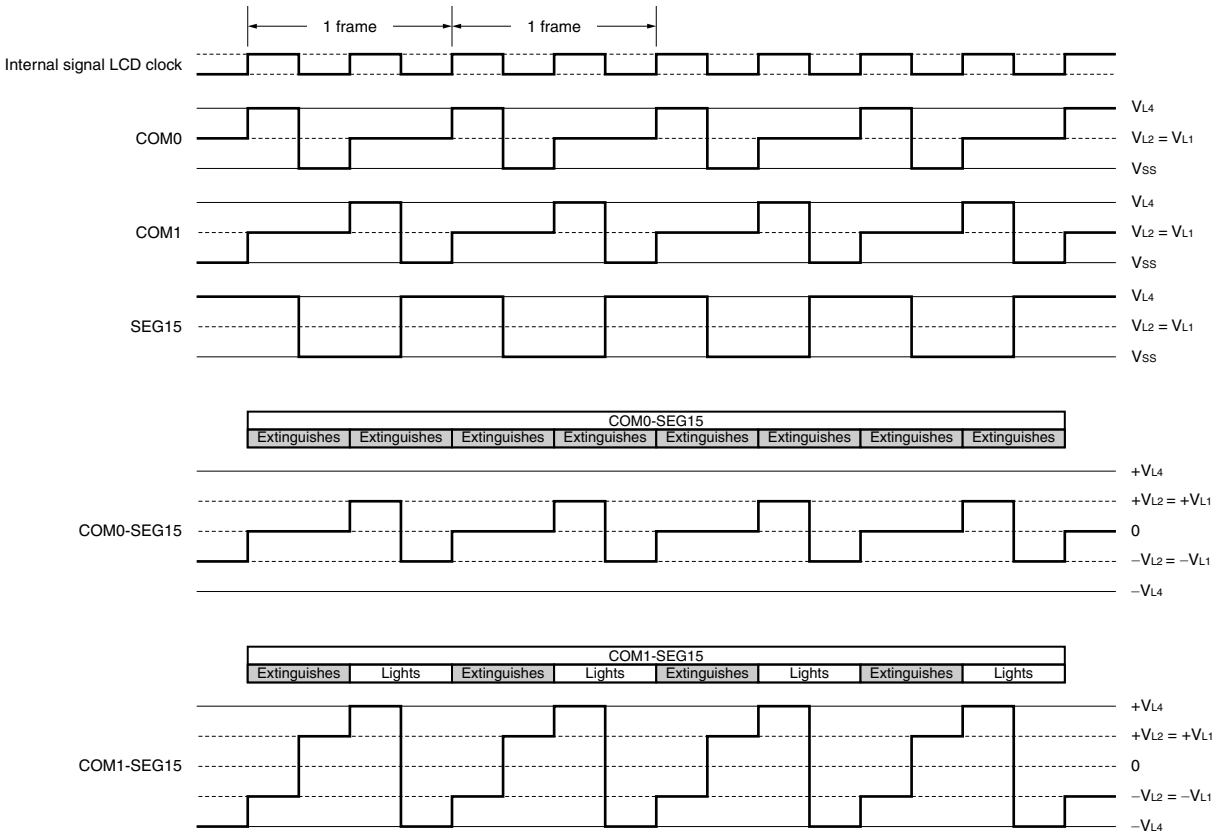
(c) 1/3 bias method (waveform A or B)

Common Signal	Segment Signal	Select Signal Level	Deselect Signal Level
		V_{SS}/V_{L4}	V_{L2}/V_{L1}
Select signal level	V_{L4}/V_{SS}	$-V_{LCD}/+V_{LCD}$	$-\frac{1}{3}V_{LCD}/+\frac{1}{3}V_{LCD}$
Deselect signal level	V_{L1}/V_{L2}	$-\frac{1}{3}V_{LCD}/+\frac{1}{3}V_{LCD}$	$+\frac{1}{3}V_{LCD}/-\frac{1}{3}V_{LCD}$

(d) 1/4 bias method (waveform A or B)

Common Signal	Segment Signal	Select Signal Level	Deselect Signal Level
		V_{SS}/V_{L4}	V_{L2}
Select signal level	V_{L4}/V_{SS}	$-V_{LCD}/+V_{LCD}$	$-\frac{1}{2}V_{LCD}/+\frac{1}{2}V_{LCD}$
Deselect signal level	V_{L1}/V_{L3}	$-\frac{1}{4}V_{LCD}/+\frac{1}{4}V_{LCD}$	$+\frac{1}{4}V_{LCD}/-\frac{1}{4}V_{LCD}$

Figure 16-31. Two-Time-Slice LCD Drive Waveform Examples Between SEG15 and Each Common Signals (1/2 Bias Method)



16.10.5 Eight-time-slice display example

Figure 16-40 shows how the 15x8 dot LCD panel having the display pattern shown in Figure 16-39 is connected to the segment signals (SEG4 to SEG18) and the common signals (COM0 to COM7). This example displays data “123” in the LCD panel. The contents of the display data register (addresses F0404H to F0412H) correspond to this display.

The following description focuses on numeral “3.” (∃) displayed in the first digit. To display “3.” in the LCD panel, it is necessary to apply the select or deselect voltage to the SEG4 to SEG8 pins according to Table 16-19 at the timing of the common signals COM0 to COM7; see Figure 16-39 for the relationship between the segment signals and LCD segments.

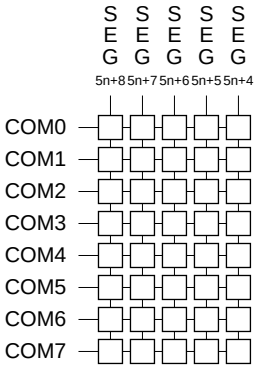
Table 16-19. Select and Deselect Voltages (COM0 to COM7)

Segment / Common	SEG4	SEG5	SEG6	SEG7	SEG8
COM0	Select	Select	Select	Select	Select
COM1	Deselect	Select	Deselect	Deselect	Deselect
COM2	Deselect	Deselect	Select	Deselect	Deselect
COM3	Deselect	Select	Deselect	Deselect	Deselect
COM4	Select	Deselect	Deselect	Deselect	Deselect
COM5	Select	Deselect	Deselect	Deselect	Select
COM6	Deselect	Select	Select	Select	Deselect
COM7	Deselect	Deselect	Deselect	Deselect	Deselect

According to the above, it is determined that the display data register location (F0404H) that corresponds to SEG4 must contain 00110001.

Figure 16-41 shows examples of LCD drive waveforms between the SEG4 signal and each common signal. When the select voltage is applied to SEG4 at the timing of COM0, a waveform is generated to turn on the corresponding LCD segment.

Figure 16-39. Eight-Time-Slice LCD Display Pattern and Electrode Connections



Remark 80-pin products: n = 0 to 8

17.4 Operations of Multiplier and Divider/Multiply-Accumulator

17.4.1 Multiplication (unsigned) operation

- Initial setting
  - <1> Set the multiplication/division control register (MDUC) to 00H.
  - <2> Set the multiplicand to multiplication/division data register A (L) (MDAL).
  - <3> Set the multiplier to multiplication/division data register A (H) (MDAH).
    (There is no preference in the order of executing steps <2> and <3>. Multiplication operation is automatically started when the multiplier and multiplicand are set to the MDAH and MDAL registers, respectively.)
- During operation processing
  - <4> Wait for at least one clock. The operation will end when one clock has been issued.
- Operation end
  - <5> Read the product (lower 16 bits) from multiplication/division data register B (L) (MDBL).
  - <6> Read the product (higher 16 bits) from multiplication/division data register B (H) (MDBH).
    (There is no preference in the order of executing steps <5> and <6>.)
- Next operation
  - <7> Start with the initial settings of each step to change the operation mode.
    When the same operation mode is used sequentially, settings <1> and <2> can be omitted.

Remark Steps <1> to <7> correspond to <1> to <7> in Figure 17-6.

Figure 17-6. Timing Diagram of Multiplication (Unsigned) Operation (2 × 3 = 6)

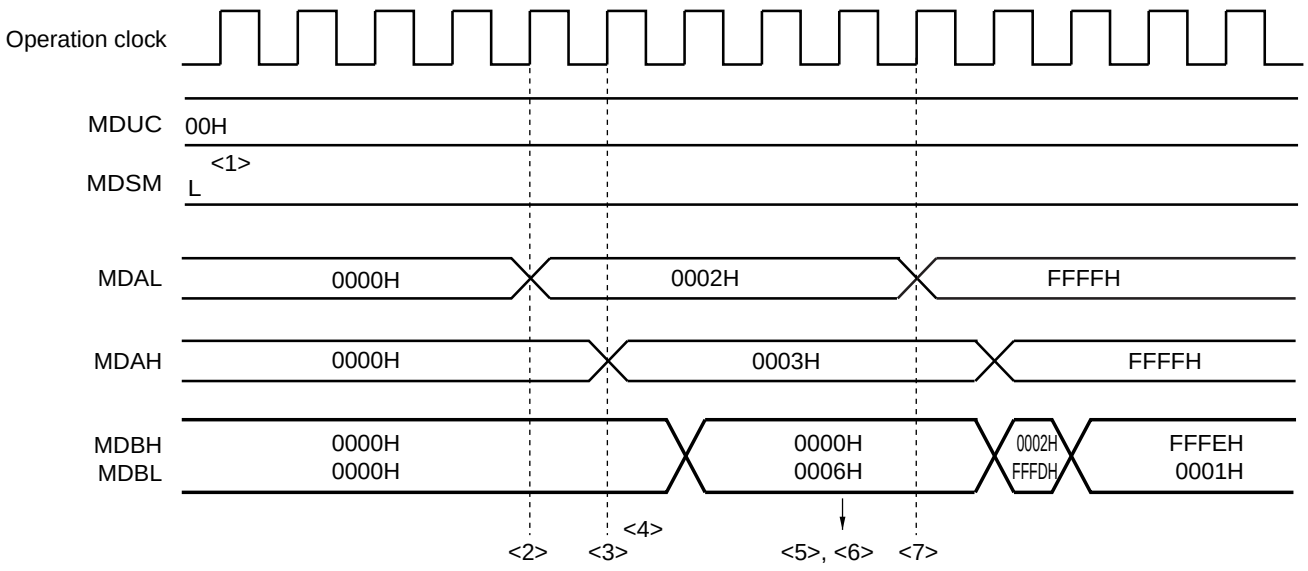
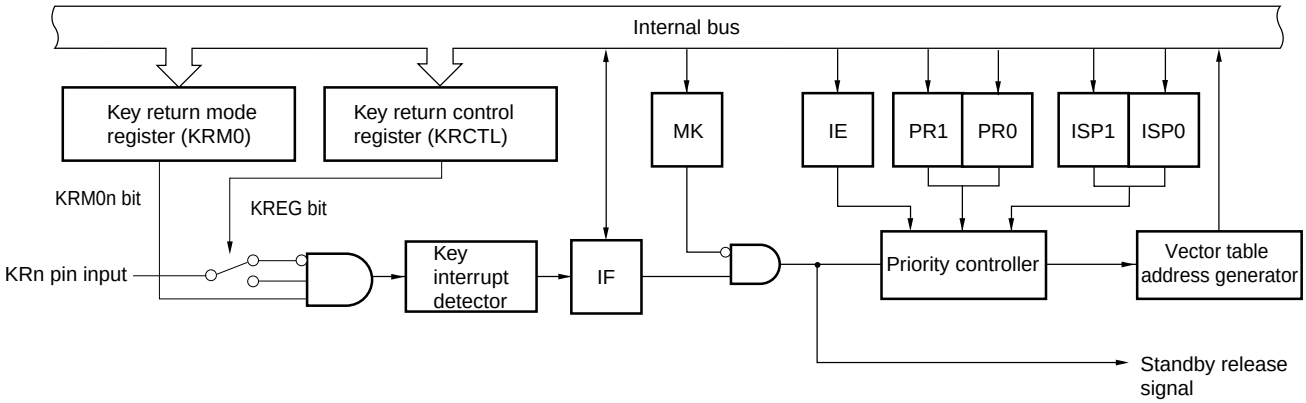
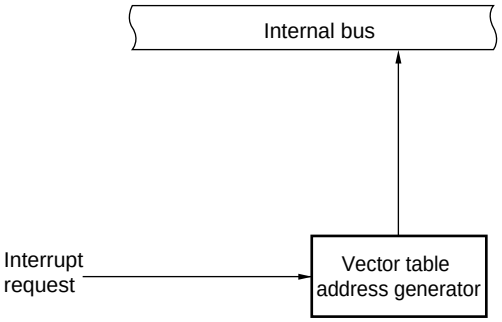


Figure 19-1. Basic Configuration of Interrupt Function (2/2)

(C) External maskable interrupt (INTKR)



(D) Software interrupt



IF: Interrupt request flag
IE: Interrupt enable flag
ISP0: In-service priority flag 0
ISP1: In-service priority flag 1
MK: Interrupt mask flag
PR0: Priority specification flag 0
PR1: Priority specification flag 1

Remark 64-pin: n = 0 to 4, 7
80-pin: n = 0 to 7

28.6 Security Settings

The RL78 microcontroller supports a security function that prohibits rewriting the user program written to the internal flash memory, so that the program cannot be changed by an unauthorized person.

The operations shown below can be performed using the Security Set command.

- Disabling block erase
  Execution of the block erase command for a specific block in the flash memory is prohibited during serial programming. However, blocks can be erased by means of self programming.

- Disabling write
  Execution of the write command for entire blocks in the flash memory is prohibited during serial programming. However, blocks can be written by means of self programming.
  After the security settings are specified, releasing the security settings by the Security Release command is enabled by a reset.

- Disabling rewriting boot cluster 0
  Execution of the block erase command and write command on boot cluster 0 (00000H to 00FFFH) in the code flash memory is prohibited by this setting.

The block erase, write commands and rewriting boot cluster 0 are enabled by the default setting when the flash memory is shipped. Security can be set by serial programming and self programming. Each security setting can be used in combination.

Table 28-11 shows the relationship between the erase and write commands when the RL78 microcontroller security function is enabled.

Caution The security function of the dedicated flash programmer does not support self-programming.

Remark To prohibit writing and erasing during self-programming, use the flash shield window function (see **28.5.3** for detail).

(8) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (slave mode, SCKp... external clock input)

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCKp cycle time[Note 1]	t_{KCY2}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V	20 MHz < f_{MCK}	12/f_{MCK}		–		–		ns
			8 MHz < f_{MCK} ≤ 20 MHz	10/f_{MCK}		–		–		ns
			4 MHz < f_{MCK} ≤ 8 MHz	8/f_{MCK}		16/f_{MCK}		–		ns
			f_{MCK} ≤ 4 MHz	6/f_{MCK}		10/f_{MCK}		10/f_{MCK}		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V	20 MHz < f_{MCK}	16/f_{MCK}		–		–		ns
			16 MHz < f_{MCK} ≤ 20 MHz	14/f_{MCK}		–		–		ns
			8 MHz < f_{MCK} ≤ 16 MHz	12/f_{MCK}		–		–		ns
			4 MHz < f_{MCK} ≤ 8 MHz	8/f_{MCK}		16/f_{MCK}		–		ns
			f_{MCK} ≤ 4 MHz	6/f_{MCK}		10/f_{MCK}		10/f_{MCK}		ns
		1.8 V (2.4 V[Note 2]) ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V[Note 3]	20 MHz < f_{MCK}	36/f_{MCK}		–		–		ns
			16 MHz < f_{MCK} ≤ 20 MHz	32/f_{MCK}		–		–		ns
			8 MHz < f_{MCK} ≤ 16 MHz	26/f_{MCK}		–		–		ns
			4 MHz < f_{MCK} ≤ 8 MHz	16/f_{MCK}		16/f_{MCK}		–		ns
			f_{MCK} ≤ 4 MHz	10/f_{MCK}		10/f_{MCK}		10/f_{MCK}		ns
SCKp high-/low-level width	t_{KH2}, t_{KL2}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V		t_{KCY2}/2 – 12		t_{KCY2}/2 – 50		t_{KCY2}/2 – 50		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V		t_{KCY2}/2 – 18		t_{KCY2}/2 – 50		t_{KCY2}/2 – 50		ns
		1.8 V (2.4 V[Note 2]) ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V[Note 3]		t_{KCY2}/2 – 50		t_{KCY2}/2 – 50		t_{KCY2}/2 – 50		ns
SIp setup time (to SCKp↑)[Note 4]	t_{SIK2}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V		1/f_{MCK} + 20		1/f_{MCK} + 30		1/f_{MCK} + 30		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V		1/f_{MCK} + 20		1/f_{MCK} + 30		1/f_{MCK} + 30		ns
		1.8 V (2.4 V[Note 2]) ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V[Note 3]		1/f_{MCK} + 30		1/f_{MCK} + 30		1/f_{MCK} + 30		ns
SIp hold time (from SCKp↑)[Note 5]	t_{KSI2}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V		1/f_{MCK} + 31		1/f_{MCK} + 31		1/f_{MCK} + 31		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V		1/f_{MCK} + 31		1/f_{MCK} + 31		1/f_{MCK} + 31		ns
		1.8 V (2.4 V[Note 2]) ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V[Note 3]		1/f_{MCK} + 31		1/f_{MCK} + 31		1/f_{MCK} + 31		ns
Delay time from SCKp↓ to SOp output[Note 6]	t_{KSO2}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ			2/f_{MCK} + 120		2/f_{MCK} + 573		2/f_{MCK} + 573	ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ			2/f_{MCK} + 214		2/f_{MCK} + 573		2/f_{MCK} + 573	ns
		1.8 V (2.4 V[Note 2]) ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V[Note 3], C_b = 30 pF, R_b = 5.5 kΩ			2/f_{MCK} + 573		2/f_{MCK} + 573		2/f_{MCK} + 573	ns

(**Notes** and **Caution** are listed on the next page, and **Remarks** are listed on the page after the next page.)

Absolute Maximum Ratings (T_A = 25°C) (3/3)

	Parameter	Symbol	Conditions		Ratings	Unit
<R>	Output current, high	I_{OH1}	Per pin	P00 to P07, P10 to P17, P22 to P27, P30 to P35, P40 to P47, P50 to P57, P60, P61, P70 to P77, P125 to P127, P130	–40	mA
<R>			Total of all pins –170 mA	P00 to P07, P10 to P17, P22 to P27, P30 to P35, P40 to P47, P50 to P57, P60, P61, P70 to P77, P125 to P127, P130	–170	mA
<R>		I_{OH2}	Per pin	P20, P21	–0.5	mA
			Total of all pins		–1	mA
<R>	Output current, low	I_{OL1}	Per pin	P00 to P07, P10 to P17, P22 to P27, P30 to P35, P40 to P47, P50 to P57, P60, P61, P70 to P77, P125 to P127, P130	40	mA
			Total of all pins 170 mA	P40 to P47, P130	70	mA
<R>				P00 to P07, P10 to P17, P22 to P27, P30 to P35, P50 to P57, P60, P61, P70 to P77, P125 to P127	100	mA
<R>		I_{OL2}	Per pin	P20, P21	1	mA
<R>			Total of all pins		2	mA
	Operating ambient temperature	T_A	In normal operation mode		–40 to +105	°C
			In flash memory programming mode			°C
	Storage temperature	T_{stg}			–65 to +150	°C

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

33.7.2 Internal voltage boosting method

(1) 1/3 bias method

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
LCD output voltage variation range	V_{L1}	C1 to C4[Note 1] = 0.47 μF[Note 2]	VLCD = 04H	0.90	1.00	1.08	V
			VLCD = 05H	0.95	1.05	1.13	V
			VLCD = 06H	1.00	1.10	1.18	V
			VLCD = 07H	1.05	1.15	1.23	V
			VLCD = 08H	1.10	1.20	1.28	V
			VLCD = 09H	1.15	1.25	1.33	V
			VLCD = 0AH	1.20	1.30	1.38	V
			VLCD = 0BH	1.25	1.35	1.43	V
			VLCD = 0CH	1.30	1.40	1.48	V
			VLCD = 0DH	1.35	1.45	1.53	V
			VLCD = 0EH	1.40	1.50	1.58	V
			VLCD = 0FH	1.45	1.55	1.63	V
			VLCD = 10H	1.50	1.60	1.68	V
			VLCD = 11H	1.55	1.65	1.73	V
			VLCD = 12H	1.60	1.70	1.78	V
			VLCD = 13H	1.65	1.75	1.83	V
Doubler output voltage	V_{L2}	C1 to C4[Note 1] = 0.47 μF		2 V_{L1} – 0.10	2 V_{L1}	2 V_{L1}	V
Tripler output voltage	V_{L4}	C1 to C4[Note 1] = 0.47 μF		3 V_{L1} – 0.15	3 V_{L1}	3 V_{L1}	V
Reference voltage setup time[Note 2]	t_{VWAIT1}			5			ms
Voltage boost wait time[Note 3]	t_{VWAIT2}	C1 to C4[Note 1] = 0.47 μF		500			ms

Notes 1. This is a capacitor that is connected between voltage pins used to drive the LCD.
C1: A capacitor connected between CAPH and CAPL
C2: A capacitor connected between V_{L1} and GND
C3: A capacitor connected between V_{L2} and GND
C4: A capacitor connected between V_{L4} and GND
C1 = C2 = C3 = C4 = 0.47 μF ± 30%

2. This is the time required to wait from when the reference voltage is specified by using the VLCD register (or when the internal voltage boosting method is selected (by setting the MDSET1 and MDSET0 bits of the LCDM0 register to 01B) if the default value reference voltage is used) until voltage boosting starts (VLCON = 1).

3. This is the wait time from when voltage boosting is started (VLCON = 1) until display is enabled (LCDON = 1).